2SK2315

Silicon N Channel MOS FET

REJ03G1006-0200
(Previous: ADE-208-1354)
Rev.2.00
Sep.07,2005

Application

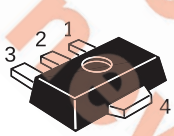
High speed power switching

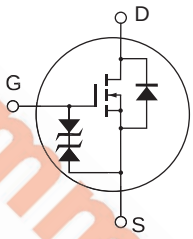
Features

- Low on-resistance
- High speed switching
- Low drive current
- 2.5 V gate drive device can be driven from 3 V source.
- Suitable for DC-DC converter, motor drive, power switch, solenoid drive

Outline

RENESAS Package code: PLZZ0004CA-A
(Package name: UPAK®)





1. Gate
2. Drain
3. Source
4. Drain

Note: Marking is “TY”

*UPAK is a trademark of Renesas Technology Corp.

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	60	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I_D	2	A
Drain peak current	$I_{D(pulse)}$*[1]	4	A
Body to drain diode reverse drain current	I_{DR}	2	A
Channel dissipation	Pch*[2]	1	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	–55 to +150	°C

Notes: 1. PW ≤ 10 µs, duty cycle ≤ 1 %
2. When using the alumina ceramic board (12.5 × 20 × 0.7mm)

Electrical Characteristics

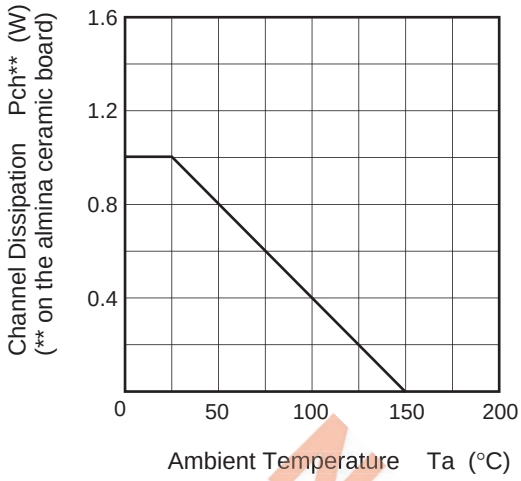
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	—	—	V	I_D = 10 mA, V_{GS} = 0
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	—	—	V	I_G = ±100 µA, V_{DS} = 0
Gate to source leak current	I_{GSS}	—	—	±5	µA	V_{GS} = ±16 V, V_{DS} = 0
Zero gate voltage drain current	I_{DSS}	—	—	5	µA	V_{DS} = 50 V, V_{GS} = 0
Gate to source cutoff voltage	$V_{GS(off)}$	0.5	—	1.5	V	I_D = 1 mA, V_{DS} = 10 V
Static drain to source on state resistance	$R_{DS(on)}$	—	0.4	0.6	Ω	I_D = 0.3 A, V_{GS} = 3 V*[3]
		—	0.35	0.45	Ω	I_D = 1 A, V_{GS} = 4 V*[3]
Forward transfer admittance	$\|y_{fs}\|$	1.5	1.8	—	S	I_D = 1 A, V_{DS} = 10 V*[3]
Input capacitance	Ciss	—	173	—	pF	V_{DS} = 10 V, V_{GS} = 0, f = 1 MHz
Output capacitance	Coss	—	85	—	pF	
Reverse transfer capacitance	Crss	—	23	—	pF	
Turn-on time	t_{on}	—	21	—	ns	I_D = 1 A, R_L = 30 Ω, V_{GS} = 10 V
Turn-off time	t_{off}	—	85	—	ns	

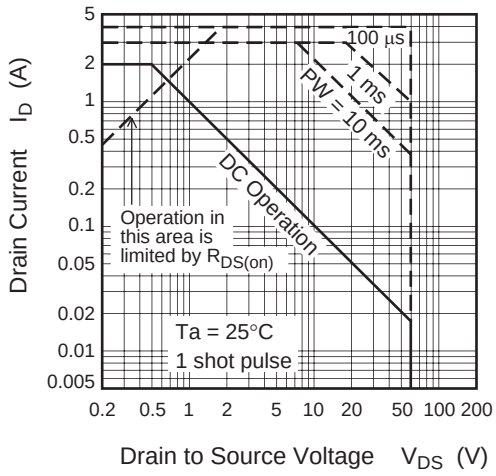
Note: 3. Pulse Test

Main Characteristics

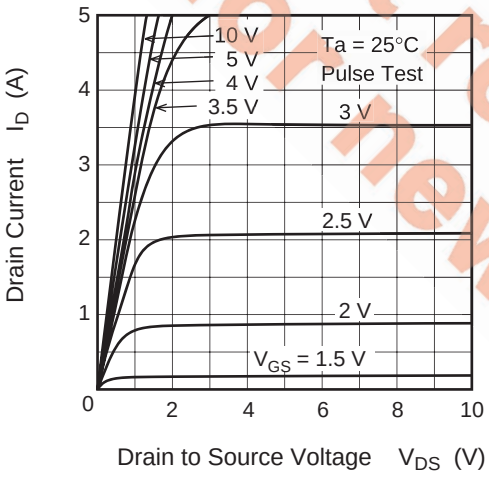
Power vs. Temperature Derating



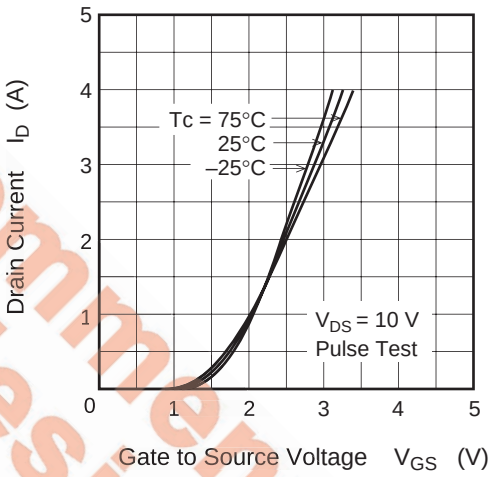
Maximum Safe Operation Area



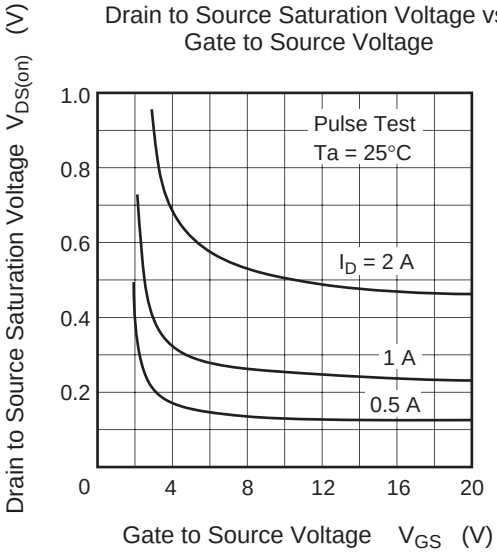
Typical Output Characteristics



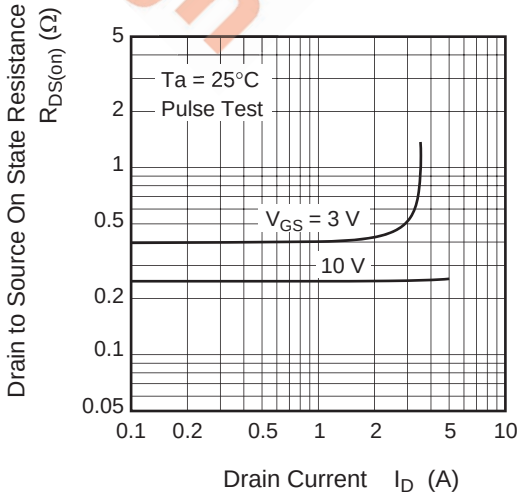
Typical Transfer Characteristics



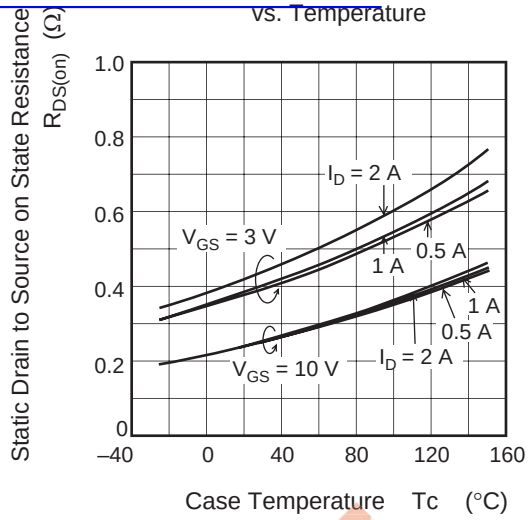
Drain to Source Saturation Voltage vs. Gate to Source Voltage



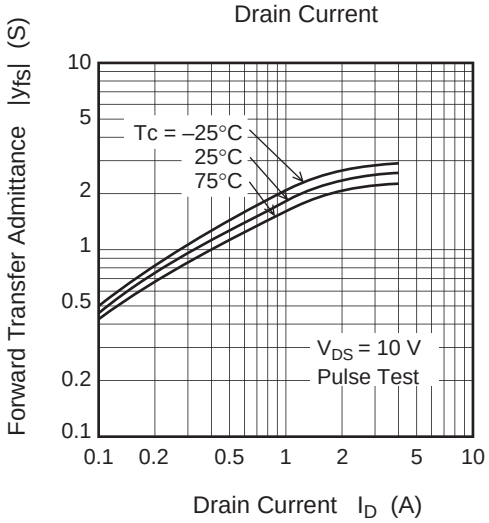
Static Drain to Source State Resistance vs. Drain Current



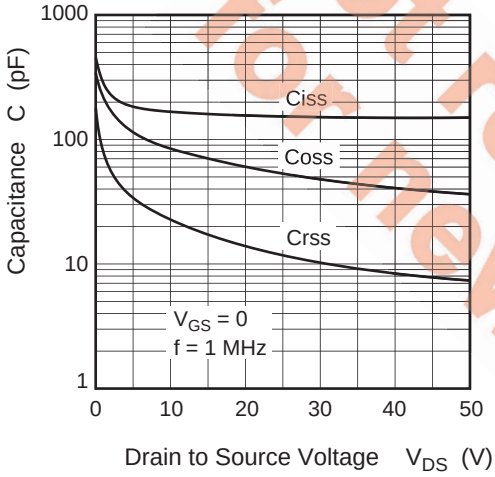
Static Drain to Source on State Resistance vs. Temperature



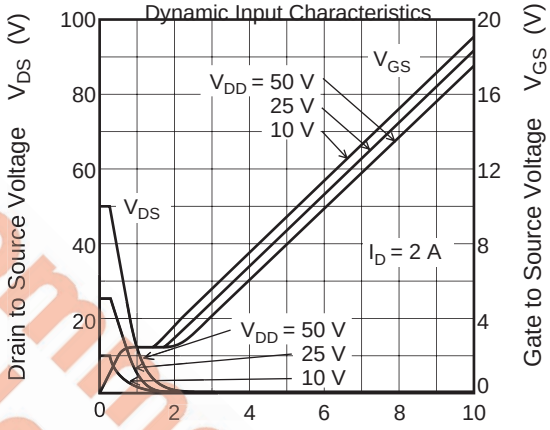
Forward Transfer Admittance vs. Drain Current



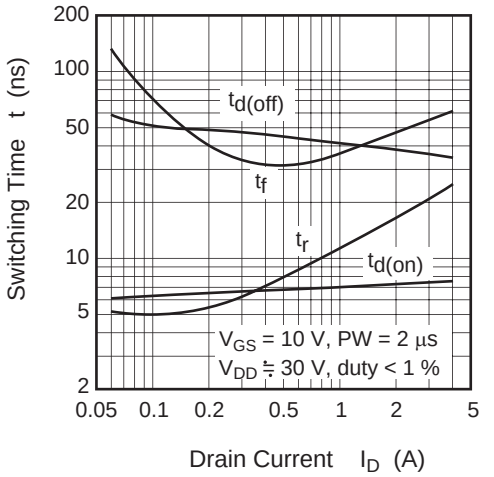
Typical Capacitance vs. Drain to Source Voltage



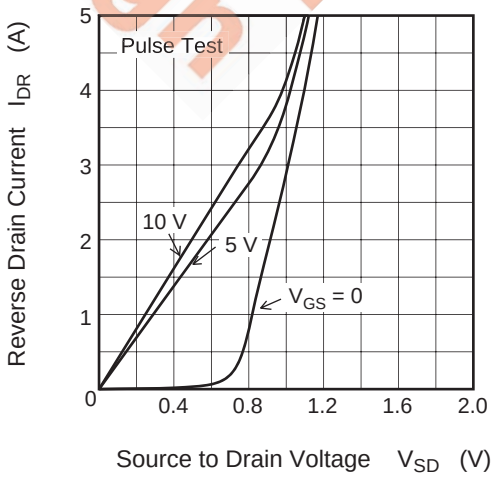
Dynamic Input Characteristics



Switching Characteristics



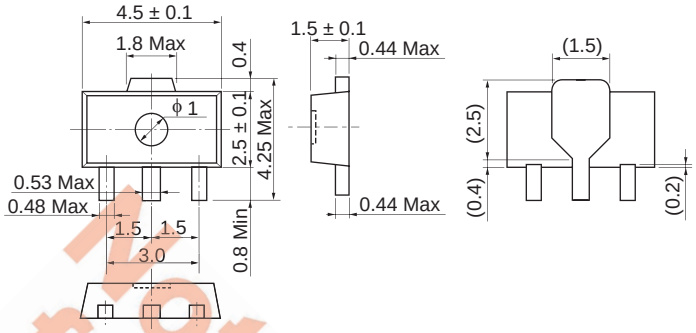
Reverse Drain Current vs. Source to Drain Voltage



Package Dimensions

JEITA Package Code	RENESAS Code	Package Name	MASS[Typ.]
SC-62	PLZZ0004CA-A	UPAK / UPAKV	0.050g

Unit: mm



Ordering Information

Part Name	Quantity	Shipping Container
2SK2315TYTL-E	1000 pcs	Taping
2SK2315TYTR-E	1000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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Renesas Technology America, Inc.
450 Holger Way, San Jose, CA 95134-1368, U.S.A
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology Hong Kong Ltd.
7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.
10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd.
Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.
Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> 2-796-3115, Fax: <82> 2-796-2145

Renesas Technology Malaysia Sdn. Bhd.
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510

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